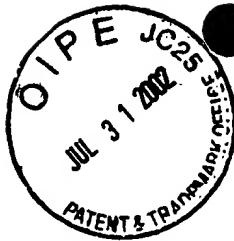


TS99-149B



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Application No. 09/755,282

July 23, 2002

TO: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

FROM: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/755,282  
File Date: 01/08/01  
Inventor: CHEN, SHENG-HSIUNG  
Examiner: MITCHELL, JAMES  
Art Unit: 2827  
Title: METHOD OF IMPROVING COPPER PAD ADHESION

RESPONSE TO OFFICE ACTION

This is in response to the office action dated May 23, 2002.

Please amend the above identified Divisional Application for  
patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited  
with the United States Postal Service as first class mail in an  
envelope addressed to: Commissioner of Patents and Trademarks,  
Washington, D.C. 20231 on July 23, 2002.

Signature

Date:

7/23/02

Stephen B. Ackerman, Reg. No. 37,761